

Introducing the SIM & eSIM concept

From the removable SIM to the soldered and interoperable eSIM

Classical SIM card

Removable

Traditional SIM concept inherited from mobile phone

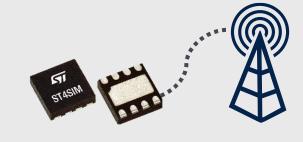


1 SIM Card = 1 operator

Embedded SIM (eSIM)

Soldered

An optimized footprint and reliable package as soldered

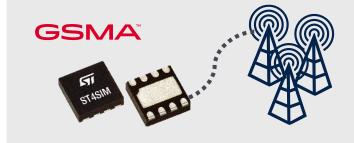


1 eSIM = 1 operator

GSMA-certified eSIM

Removable or Soldered

Possibility to change remotely the operator without replacing the SIM



1 eSIM = more operators

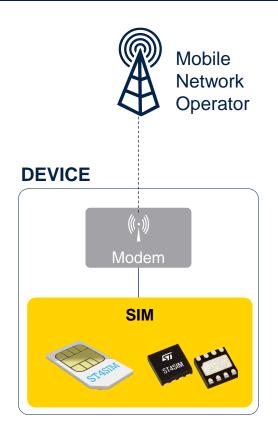






Introducing the SIM concept

A component always required to enable cellular connectivity



The SIM is

- Statically linked to a single operator
- Requires huge maintenance in case of operator swap
- Owned by operator
- Complex in term of logistic management
- Based on a secure microcontroller hardware
- Stores all information identifying the subscriber and the telecom operator (MNO/MVNO)
- Provides to the modem all features to access the cellular network
- Is available in multiple packages (removable or solderable)
- Is compliant with multiple segments requirements (IoT and Industrial)









New requirements coming from IoT

Need to ease the SIM / eSIM deployment

Future mainstream

Reprogrammable

Traditional SIM

Non-reprogrammable



IoT-enabled product manufacturers would have the ability to build devices with "blank" SIMs that could be activated in the destination country.

This functionality would make for easy equipment connectivity and allow manufacturers to offer new products in new market segments.

McKinsey & Company







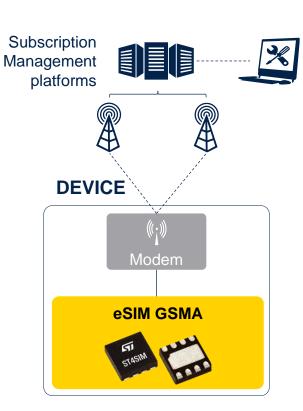


Introducing the eSIM concept

New standard product pushed by GSMA

Service

Provider





The **eSIM**, also known as an embedded UICC (eUICC), is a SIM which:

- Allows to change operator without physical SIM swapping
- Hosts multiple operator profiles only one at a time is enabled
- Is owned by an OEM
- Is available on different packages (removable or solderable)
- Is compliant with multiple segments (IoT and Industrial)
- Is compatible with LTE, 5G and LPWA^(*) networks

(*) RSP not possible under NB-IoT with eUICC M2M (SGP.02) due to the SMS missing







GSMA SGP specifications



- Version 3.2 in volume production
- Version 4.2 available for 5G



- Version 2.x in volume production
- Version 3.0 published

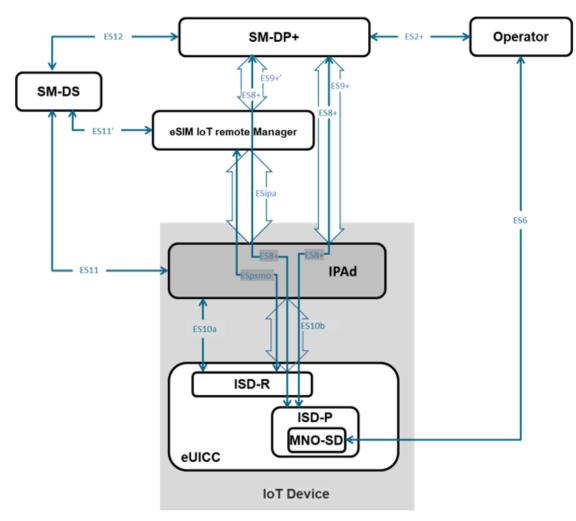


- Architecture spec SGP.31 v1.1
- Technical spec SGP.32 v1.x





SGP32 - eSIM IoT Architecture



eSIM IoT functional architecture (IPA in the IoT device)

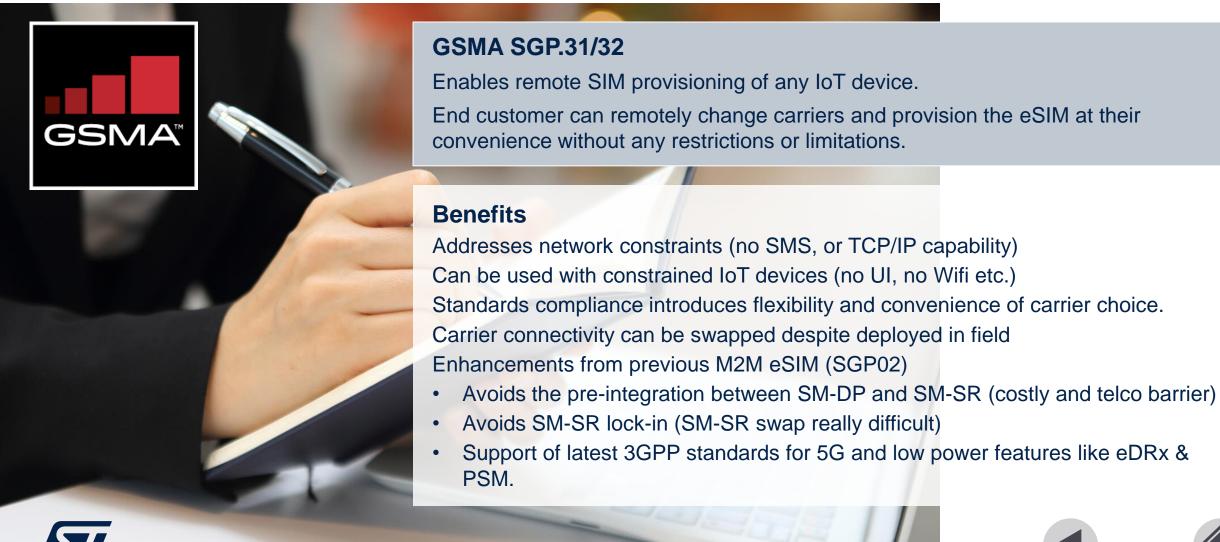








GSMA eSIM for IoT







ST4SIM OS roadmap







ST4SIM complete portfolio

A complete offer from regular M2M SIM to the eSIM for IoT

ST4SIM-100x



- Classic SIM compliant to ETSI/3GPP
- Telecom Operator partner:
 - Vodafone (*)

- Available on card plug-in and MFF2
- IoT and Industrial

ST4SIM-110x / 111x







- Classic SIM compliant to ETSI/3GPP/5G
- · Telecom Operator partner:
 - Vodafone (*)
 - **Verizon Wireless**
 - AT&T
 - Soracom
- Available on card plug-in, MFF2, WLCSP(**)
- IoT and Industrial

GSMA







GSMA



Roadmap

- · eSIM compliant to **GSMA SGP.02 v3.2** GSMA SGP.02 v4.2 - eSA certified
- Telecom Operator partner:
 - **Verizon Wireless**
 - 1GLOBAL
 - Wireless Logic
- Available on card plug-in, MFF2, WLCSP(**)
- IoT and Industrial

- · eSIM compliant to
 - GSMA SGP.32 v1.x
- Telecom Operator partner:
- Flexible bootstrap operator & elM selection
- IPA reference design
- Available on card plug-in, MFF2, WLCSP(**)
- IoT and Industrial











ST4SIM-300 ecosystem

ST4SIM-300 component

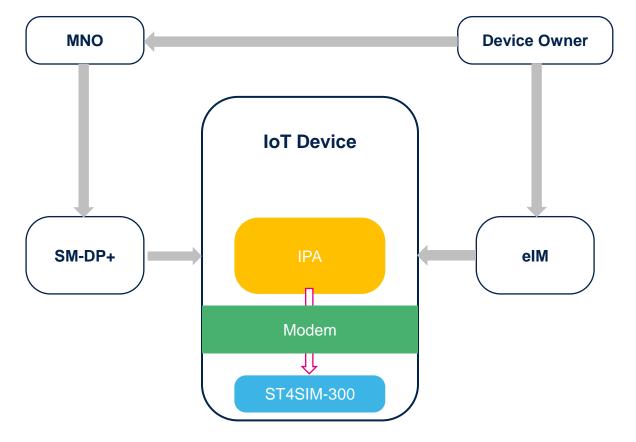
- IoT and Industrial-grade HW
- STASIM ST

- Multiple form factor
- GSMA SGP.31/SGP.32 compliant
- Targeting GSMA eSA certification



ST4SIM-300 related services

- Bootstrap options
 - Default bootstrap by ST^(*)
 - · No default bootstrap
 - · Customized bootstrap operator
- · Configurable eIM
 - · Default service by ST
 - · Custom configuration according customer request
- IPA_d reference design
 - Java based version (*)
 - C version compatible with STM32 (*)



direct & indirect profile download from SM-DP+









ST4SIM current portfolio





ST4SIM-M

Basic SIM & eSIM	Optimized and cost effective				
ST4SIM-100x	ST4SIM-100S	ST4SIM-100M			
Crypto 5G SIM & eSIM ST4SIM-110x / -111x	Advanced secure communication				
	ST4SIM-110S / ST4SIM-111S	ST4SIM-110M / ST4SIM-111M			
GSMA eSIM ST4SIM-200x	Scalable & interoperable solution				
	ST4SIM-200S	ST4SIM-200M			
GSMA 5G eSIM ST4SIM-201x	5G, Scalable & interoperable solution				
	ST4SIM-201S	ST4SIM-201M			







Package offer

Industrial	ST4SIM-100	ST4SIM-110/111		ST4SIM-200/201			ST4SIM-300	
				X				
Package	D19 (4FF / 6 contacts)	D16 (4FF / 6 contacts)	DFN8 5x6 MFF2 (Not Wettable Flank)	D16 (4FF / 6 contacts)	DFN8 5x6 MFF2 (Wettable Flank)	WLCSP (0.395mm max thickness)	DFN MFF2	WLCSP (0.330mm max thickness)
Availability	Available	Available	Available	Available	Available	Available (*)	4q23 ES 1H24 MP	1H24 (*)

^(*) Availability upon request and based on requested profile









ST4SIM ecosystem

ST4SIM component



- IoT and Industrial-grade HW
- Multiple form factor
- SIM / eSIM SoC configuration
- GSMA eSIM certified and interoperable





+ Pre-loaded connectivity from partners

Telecom Operators MNO / MVNO

+ Pre-loaded test profile



Connectivity platforms

Telecom Operators MNO / MVNO

Complete ecosystem with

- SM-SR: Subscription Manager Secure Routing
- SM-DP: Subscription Manager Data Preparation





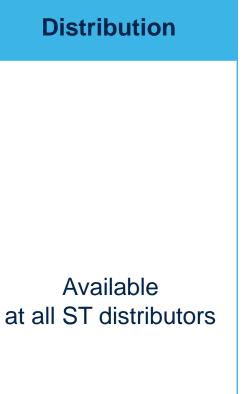






ST4SIM-200M available at e-distribution





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